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> SCGD Series > SCGD1B0201

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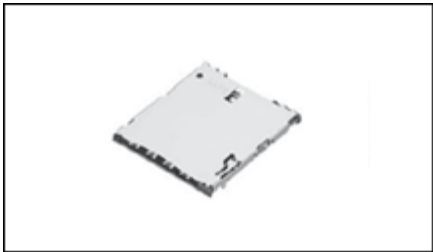
For microSIM Card (Push-push Type) SCGD Series

Detail

Part number		SCGD1B0201
Applicable media		microSIM card
Media ejection structure		Push-push type
Mounting type		Surface mounting type
Mounting style		Standard mount
Card eject stroke		3mm
Stand-off		0mm
Minimum order unit (pcs.)		1,600
Operating temperature range		-25 to +60
Voltage proof		250V AC 1 minute
Insulation resistance (Initial)		1,000MΩ min.
Contact resistance (Initial)	Connector contacts	100mΩ max.
	Detection Switch	500mΩ max.
Insertion and removal cycle		5,000 cycles
3D CAD (STEP)		Download

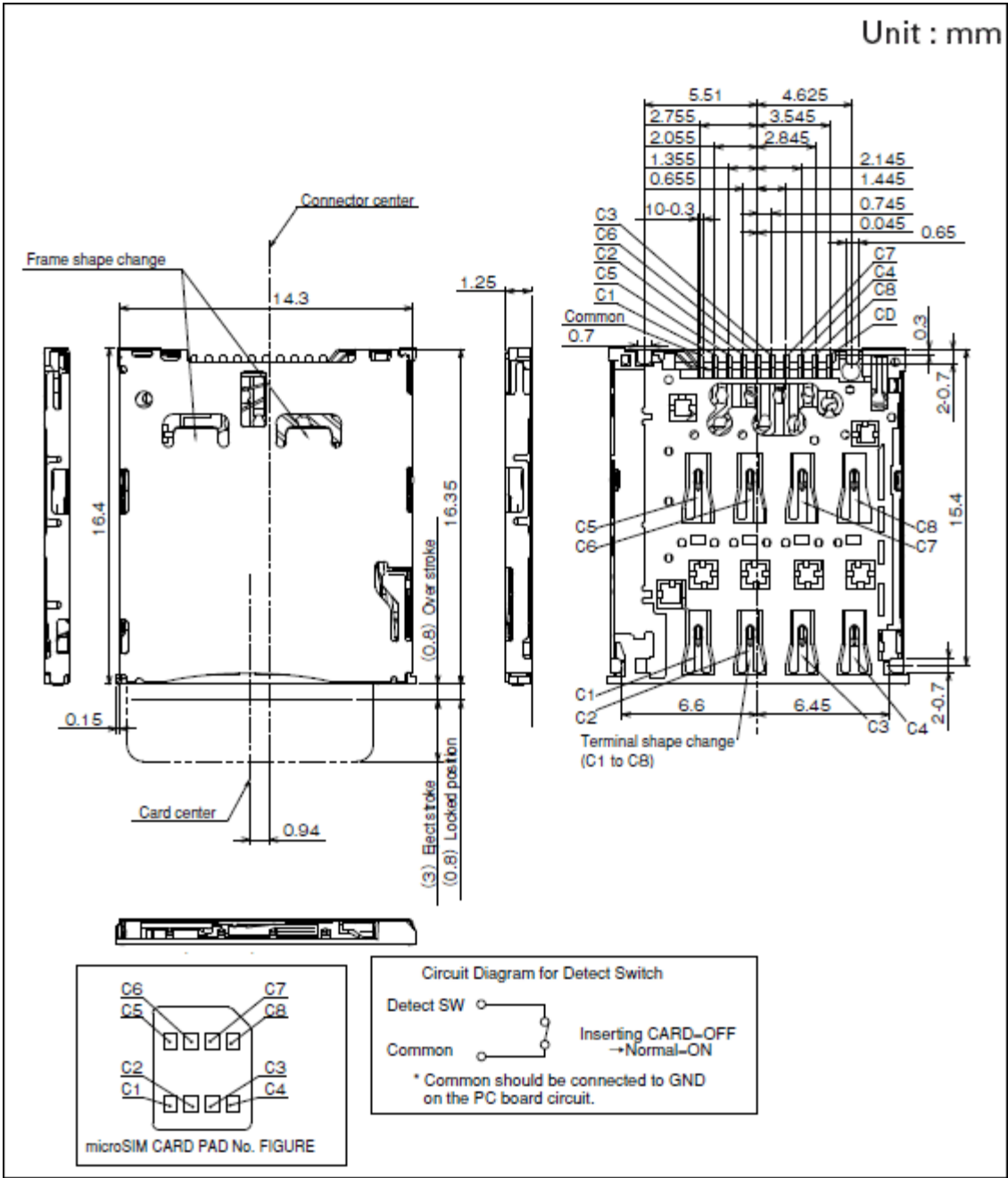
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Photo



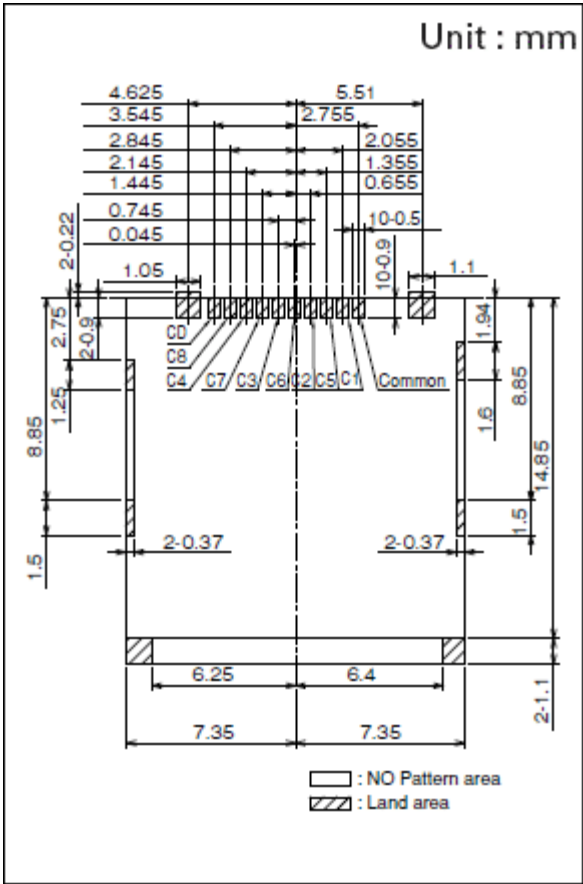
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Dimensions



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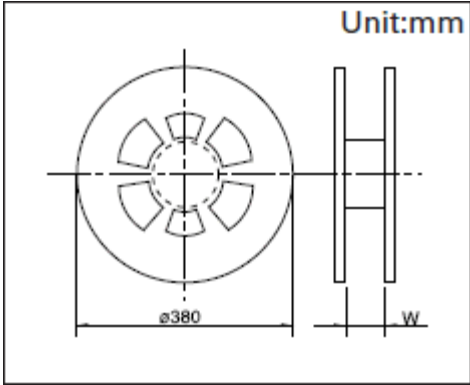
Mounting Dimensions



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Packing Specifications

Taping

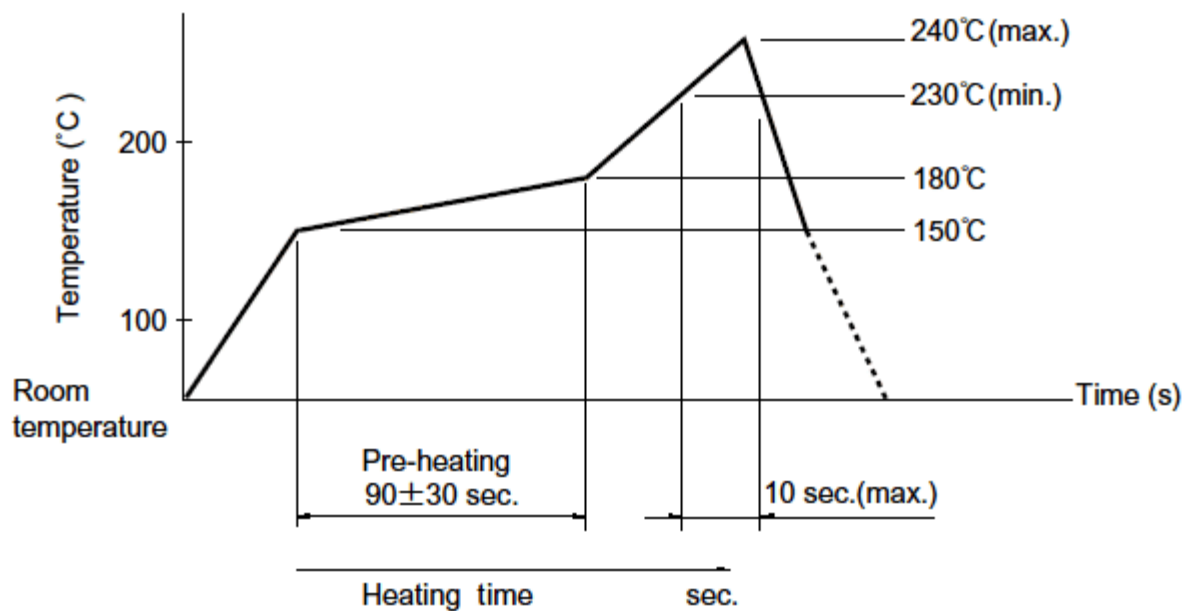


Number of packages (pcs.)	1 reel	1,600
	1 case / Japan	4,800
	1 case / export packing	9,600
Reel width W(mm)		57.5
Tape width (mm)		56
Export package measurements (mm)		403×403×303

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method
Double heating method with infrared heater.
2. Temperature measurement
Thermocouple 0.1 to 0.2 Φ CA (K) or CC (T) at soldering portion.
3. Temperature profile.



NOTE

Notes are common to this series/models.

1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
2. Please place purchase orders per minimum order unit (integer).



Inquiries about Products

For more information please contact: Products Information Center.

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